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| SUBMISSION TYPE: | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT |

CONVEYING PARTY DATA

| Name | Execution Date |
|-----------------|----------------|
| Cheng-Chung Hsu | 03/04/2008 |

RECEIVING PARTY DATA

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| City: | HsinChu | |
| State/Country: | TAIWAN | |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---------------------|----------|
| Application Number: | 12017348 |

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> PATENT REEL: 020613 FRAME: 0131

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ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

| ASSIGNOR | (S) (Inventors): | | | |
|-----------------|--|----------------------|---|--|
| Name: | Cheng-Chung Hsu | | Nationality: R.O.C. | |
| Hereby sells, a | ssigns and transfers to | | | |
| ASSIGNEE(S |): | | | |
| Name: | Realtek Semiconductor Corp. | | | |
| Address: | 2 Innovation Rd. II, Science Park, HsinChu 30076, Taiwan, R.O.C. | | | |
| any and all im | provements which are d | isclosed in the inve | entire right, title, and interest in and to interest in and interest in an and interest in an analysis in | |
| Which is four | nd in : | | | |
| (a) | U.S. patent application | executed on even of | late | |
| (b) | U.S. patent application | executed on | | |
| (c) <u>+</u> | U.S. application serial | no. 12/017, | 3.4.8 | |
| (d) | patent no. | issued | | |
| | | | | |

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

| IN WITNESS WHEREOF, We hav signing). (請發明人務必簽署上列日期・) | ve hereunto set hand and seal this | (Date of |
|---|--------------------------------------|-------------------|
| (Type name of inventor) Cheng-Chung Hsu | Signature of INVENTOR Cheng-Chung 7 | 03/64/2008 154 |

RECORDED: 03/06/2008